

# UT6J3

-20V Pch+Pch Power MOSFET

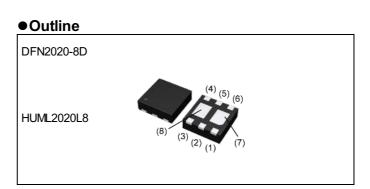
V <sub>DSS</sub>	-20V
R <sub>DS(on)</sub> (Max.)	85mΩ
Ι <sub>D</sub>	±3A
P <sub>D</sub>	2W

## Features

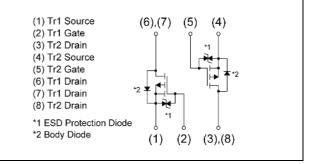
- 1) Low on resistance
- 2) Small Surface Mount Package
- 3) Pb-free plating ; RoHS compliant
- 4) Halogen Free

Application

Switching



## Inner circuit



## Packaging specifications

Packing	Embossed Tape
Reel size (mm)	180
Tape width (mm)	8
Quantity (pcs)	3000
Taping code	TCR
Marking	J03
	Reel size (mm) Tape width (mm) Quantity (pcs) Taping code

# • Absolute maximum ratings ( $T_a = 25^{\circ}C$ ,unless otherwise specified) <Tr1 and Tr2>

- Cu			
Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	-20	V
Continuous drain current	I <sub>D</sub> *1	±3	Α
Pulsed drain current	1 <sub>DP</sub> *2	±12	Α
Gate - Source voltage	V <sub>GSS</sub>	0 to -8	V
Avalanche current, single pulse	I <sub>AS</sub> *3	-3	Α
Avalanche energy, single pulse	E <sub>AS</sub> *3	0.6	mJ
Power dissipation	P <sub>D</sub> <sup>*4</sup>	2	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

## •Thermal resistance

Deremeter	Symbol	Values			Linit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	$R_{thJA}^{*4}$	-	-	62.5	°C/W

# •Electrical characteristics (T<sub>a</sub> = 25°C) <Tr1 and Tr2>

Deremeter	Currence of	Conditions	Values			- Unit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	UTIIL	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -1mA	-20	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = -1mA referenced to 25°C	-	-9.3	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V	-	-	-1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = -8V, V <sub>DS</sub> = 0V	-	-	-10	μA	
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1mA	-0.3	-	-1.0	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$			1.8	-	mV/°C	
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3.0A	-	60	85		
Static drain - source on - state resistance	<b>D</b> *5	V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -1.5A	-	65	95		
	R <sub>DS(on)</sub> *5	V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -1.5A	-	95	155	mΩ	
		V <sub>GS</sub> = -1.5V, I <sub>D</sub> = -0.6A	-	130	260		
Forward Transfer Admittance	Y <sub>fs</sub>  * <sup>5</sup>	V <sub>DS</sub> = -10V, I <sub>D</sub> = -3A	4	-	-	S	

\*1 Limited only by maximum temperature allowed.

\*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

\*3 L  $\simeq$  0.1mH, V\_{DD} = -10V, R\_G = 25 $\Omega$ , Starting T\_j = 25°C Fig.3-1,3-2

\*4 Mounted on a Cu board (40×40×0.8mm)

\*5 Pulsed



# •Electrical characteristics ( $T_a = 25^{\circ}C$ ) <Tr1 and Tr2>

Deremeter	Cump of	Conditions	Values			Unit	
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub>	C <sub>iss</sub> V <sub>GS</sub> = 0V		2000	-		
Output capacitance	C <sub>oss</sub> V <sub>DS</sub> = -10V		-	75	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	C <sub>rss</sub> f = 1MHz		70	-		
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq -10V, V_{GS} = -4.5V$	-	10	-		
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = -1.5A	-	30	-		
Turn - off delay time	t <sub>d(off)</sub> *5	R <sub>L</sub> = 66.5Ω	-	120	-	ns	
Fall time	$t_{f}^{*5}$	R <sub>G</sub> = 10Ω	-	35	-		

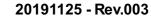
# •Gate charge characteristics ( $T_a = 25^{\circ}C$ ) <Tr1 and Tr2>

Deremeter	Cumphel	Conditions	Values			1 1.0.14
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*5}$		-	8.5	-	
Gate - Source charge	$Q_{gs}^{*5}$	V <sub>DD</sub> ≃ -10V, I <sub>D</sub> = -3.0A V <sub>GS</sub> = -4.5V	-	3.5	-	nC
Gate - Drain charge	${\sf Q}_{\sf gd}{}^{*5}$		-	1.5	-	

# ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

<Tr1 and Tr2>

Parameter	Sympol	Conditions	Values			Unit	
	Symbol	Conditions	Min.	Тур.	Max.	UIII	
Continuous forward current	۱ <sub>S</sub> *1	T - 25°0	-	-	-3	•	
Pulse forward current	$I_{SP}^{*2}$	T <sub>a</sub> = 25°C	-	-	-12	A	
Forward voltage	$V_{SD}^{*5}$	V <sub>GS</sub> = 0V, I <sub>S</sub> = -3.0A	-	-	-1.2	V	



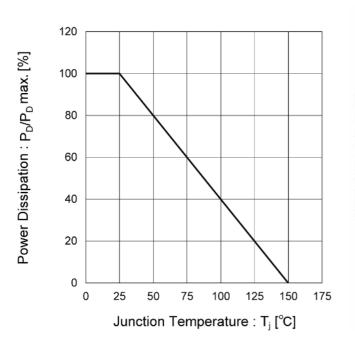


Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

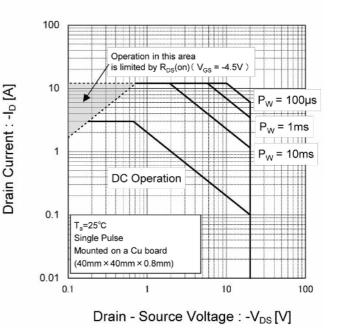
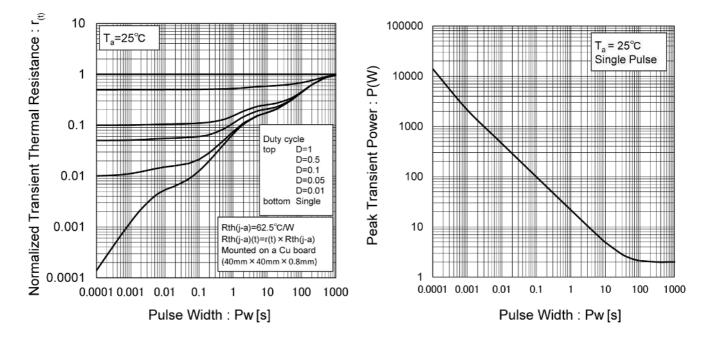
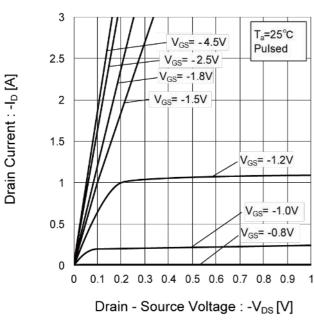


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power Dissipation



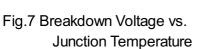


## Fig.5 Typical Output Characteristics(I)

3 T<sub>a</sub>=25°C V<sub>GS</sub>= -4.5V Pulsed V<sub>GS</sub>= -2.5V 2.5 <sub>GS</sub>= -1.8V /<sub>GS</sub>= -1.5V 2 V<sub>GS</sub>= -1.2V 1.5 1 0.5 V<sub>GS</sub>= -1.0V V<sub>GS</sub>= -0.8V 0 2 3 5 4 6 7 8 9 10 0 1 Drain - Source Voltage : -V<sub>DS</sub> [V]

Drain Current : -I<sub>D</sub> [A]

# Fig.6 Typical Output Characteristics(II)



1.2 Normalized Breakdown Voltage : -V<sub>(BR)DSS</sub> V<sub>GS</sub> = 0V  $I_D = -1mA$ Pulsed 1.1 1.0 0.9 0.8 -50 25 -25 0 50 75 100 125 150 Junction Temperature : T<sub>i</sub> [°C]



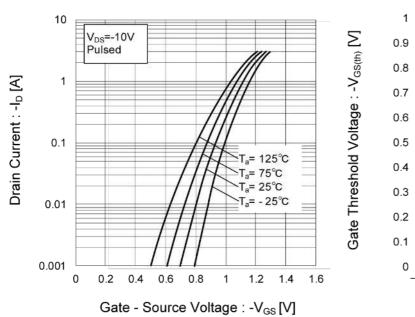
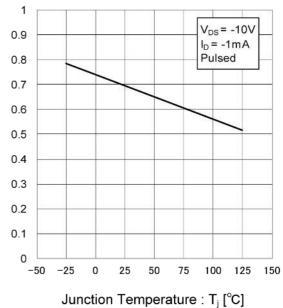
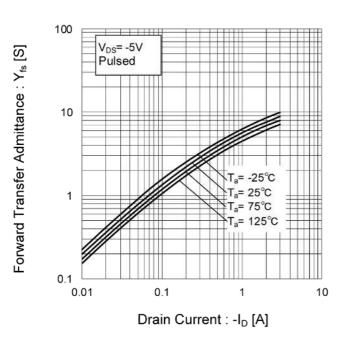


Fig.8 Typical Transfer Characteristics

## Fig.9 Gate Threshold Voltage vs. Junction Temperature



# Fig.10 Forward Transfer Admittance vs. Drain Current





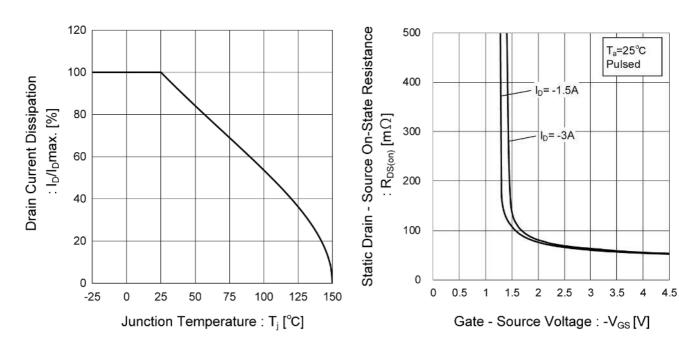


Fig.11 Drain Current Derating Curve

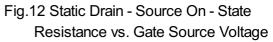
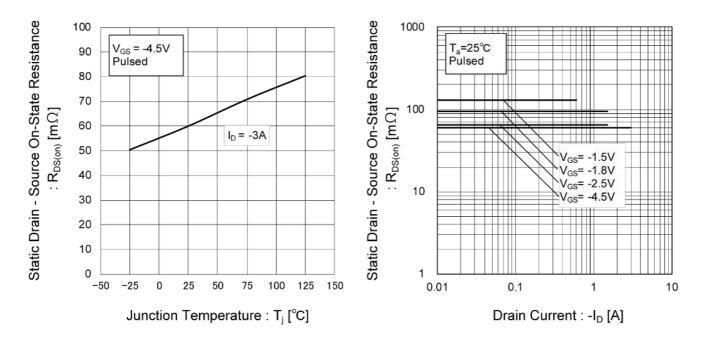


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)



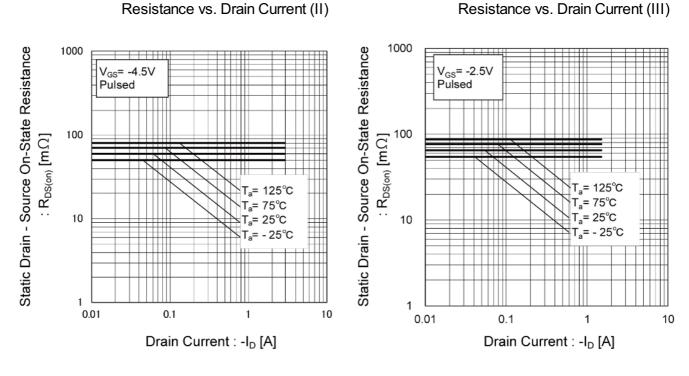


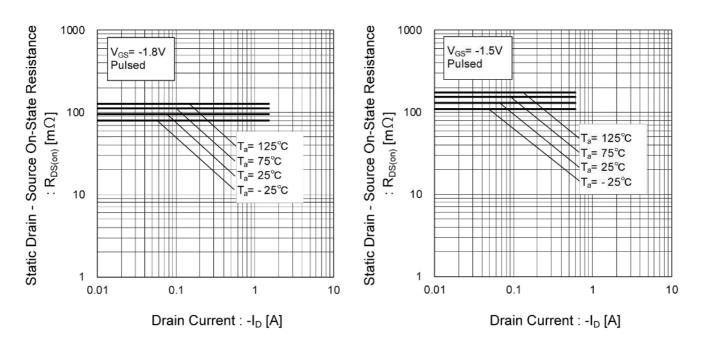
Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

Fig.17 Static Drain - Source On - State

Resistance vs. Drain Current (IV)

Fig.18 Static Drain - Source On - State Resistance vs. Drain Current (V)

Fig.16 Static Drain - Source On - State





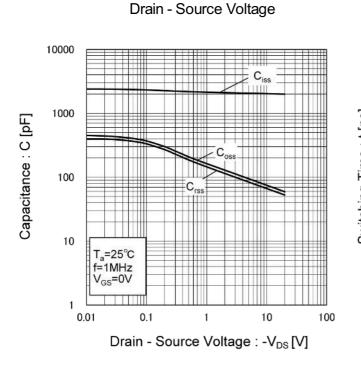


Fig.19 Typical Capacitances vs.

### Fig.20 Switching Characteristics

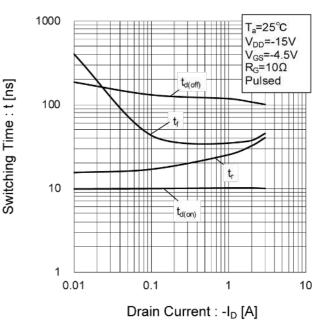


Fig.21 Typical Gate Charge

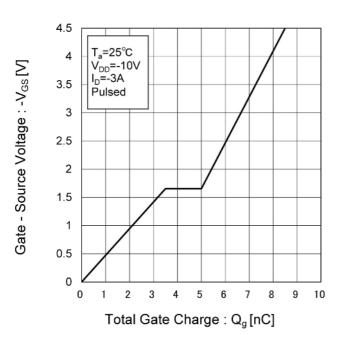
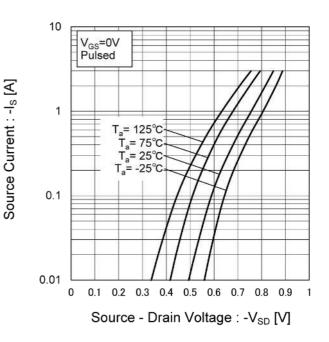


Fig.22 Source Current vs. Source Drain Voltage



# •Measurement circuits <It is the same for the Tr1 and Tr2>



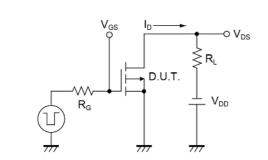


Fig.2-1 Gate Charge Measurement Circuit

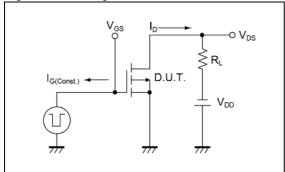


Fig.3-1 Avalanche Measurement Circuit

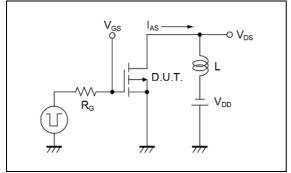
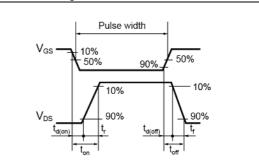


Fig.1-2 Switching Waveforms





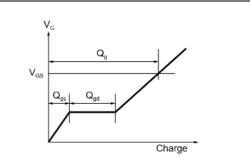
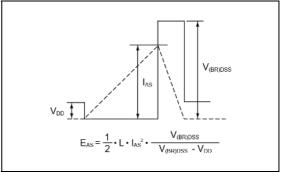


Fig.3-2 Avalanche Waveform

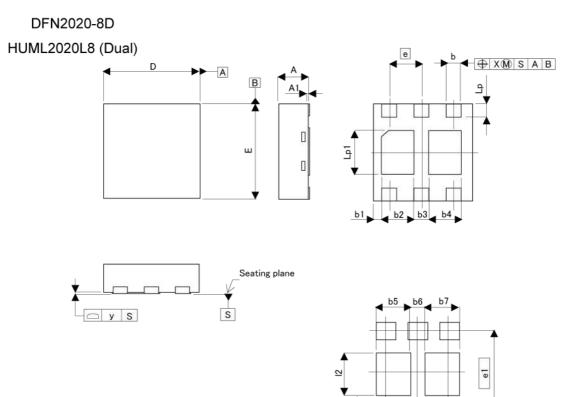


## Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.



#### Dimensions



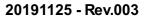
Pattern of terminal position areas [Not a pattern of soldering pads]

е

b8

DIM -	MILIMETERS		INC	HES
	MIN	MAX	MIN	MAX
A	0.55	0.65	0.022	0.026
A1	0.00	0.05	0.000	0.002
b	0.25	0.35	0.010	0.014
b1	0.	25	0.0	)10
b2	0.60	0.70	0.024	0.028
b3	0	.3	0.0	)12
b4	0.60	0.70	0.024	0.028
D	1.90	2.10	0.075	0.083
E	1.90	2.10	0.075	0.083
е	0.65		0.026	
Lp	0.225	0.325	0.009	0.013
Lp1	0.80	1.00	0.031	0.039
x	-	0.10		0.004
у	-	0.10		0.004
<b>DHA</b>	MILIME	TERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b5	÷.	0.70	3.	0.028
b6	0.20	0.30	0.008	0.012
b7	-	0.70	(H)	0.028
b8	-	0.45		0.018
e1	1.7	725	0.0	)68
11	-	0.425	1072	0.017
12		1.00	1.4	0.039

Dimension in mm/inches



# Notice

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(Note1) Medical Equipment Classification of the Specific Applications
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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSIII	CLASSⅢ	CLASSI

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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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